

Appl. No. 09/548,946
Amdt. dated March 22, 2004
Reply to Office Action of December 23, 2003

PATENT

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-4. (canceled).

Claim 5. (previously presented) A chip device comprising:
a leadframe including source and gate connections;
a bumped die including solder bumps on a top side, the bumped die being
attached to the leadframe such that the solder bumps contact the source and gate connections;
and
a copper clip attached to a backside of the bumped die such that the copper clip
couples drain regions of the bumped die and a lead rail.

Claim 6. (previously presented) A chip device in accordance with claim 5
wherein the copper clip is attached to the bumped die with solder paste.

Claim 7. (previously presented) A chip device of claim 5 wherein the lead rail
has a v-groove.

Claim 8. (previously presented) A chip device of claim 5 wherein the bumped die
comprises an under bump material.

Claim 9. (previously presented) A chip device of claim 5 wherein the lead frame
and the lead rail comprise copper.

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Claim 10. (new) A chip device comprising:
a leadframe including source and gate connections;
a bumped die including solder bumps on a frontside, the bumped die being attached to the leadframe such that the solder bumps contact the source and gate connections;
a copper clip attached to a backside of the bumped die and having an edge;
a lead rail including leads and a v-groove, wherein the edge of the copper clip is in the v-groove; and
solder paste coupling the edge of the copper clip and the v-groove of the lead rail.

Claim 11. (new) A chip device in accordance with claim 10 wherein the copper clip is attached to the bumped die with solder paste.

Claim 12. (new) A chip device of claim 10 wherein the lead rail comprises copper.

Claim 13. (new) A chip device of claim 10 further comprising apertures in the leadframe.

Claim 14. (new) A chip device of claim 10 wherein the lead frame and the lead rail comprise copper.